



# MYC-YT113i CPU Module Overview





- ✓ Up to 1.2GHz Allwinner T113-i Dual-core ARM Cortex-A7 MPU with Single-core HiFi4 DSP
- ✓ 512MB/1GB DDR3, 4GB/8GB eMMC, 32KB EEPROM
- ✓ 1.0mm pitch 140-pin Stamp Hole Expansion Interface + 50-pin LGA
- ✓ Supports Running Linux OS





Measuring only 37mm by 39mm, the MYC-YT113i CPU Module has the same 140-pin Castellated-Hole expansion interface pinout signals with the MYC-YT113X CPU Module but supporting larger capacities of external DDR3 memory (512MB/1GB), while the MYC-YT113X is fixed at 128MB on-chip DDR3 memory. It is based on **Allwinner T113-i** processor which features up to 1.2GHz Dual-core ARM Cortex-A7 MPU with a RISV slave core and a single-core HiFi4 DSP. The standard configurations have 4GB or 8GB eMMC options. It is capable of running Linux and suitable for applications such as HMI, industrial automation, display and control terminals.





MYC-YT113i CPU Module (Top-view and Bottom-view)

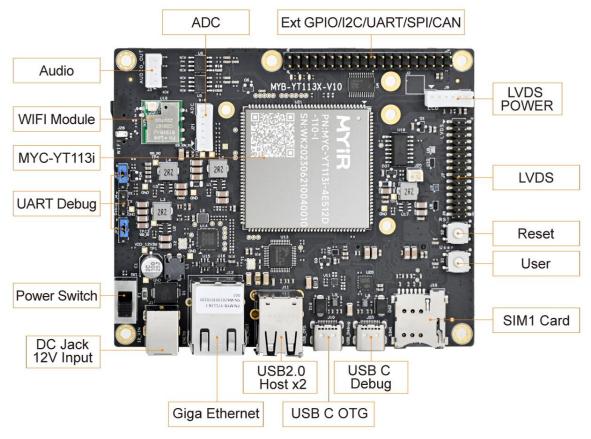


MYC-YT113i Function Block Diagram

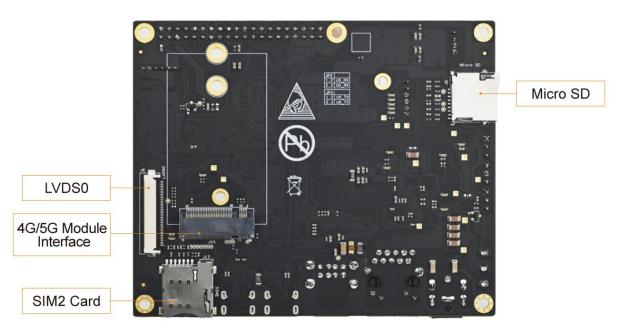




The MYD-YT113i Development Board is built around the MYC-YT113i CPU Module and has explored a rich set of peripherals and interfaces to the base board including serial ports, one Gigabit Ethernet, two USB 2.0 HOST and one USB 2.0 OTG, one Micro SD card slot, one M.2 Socket for USB based 4G/5G LTE Module with two SIM card holders, one USB2.0 based WiFi module, one GPIO/I2C/UART/SPI/CAN extension header, Audio input/output and LVDS display interface.



MYD-YT113i Development Board Top-view



MYD-YT113i Development Board Bottom-view

MYIR also offers MY-WIREDCOM RPI Module (RS232/RS485/CAN) and MY-LVDS070C LCD Module as options for the MYD-YT113i Development Board to enhance the functionality of the board.





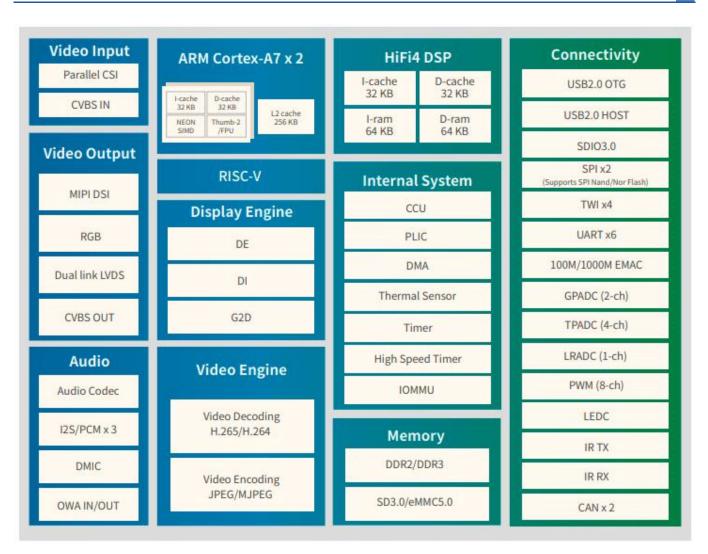
### **Hardware Specification**

The MYC-YT113i CPU Module is using 13 x 13 mm, 337-LFBGA package Allwinner T113-i processor which is the Multi-Media decoding platform. T113-i integrates a 64-bit XuanTie C906 RISC-V CPU, a dual-core Arm Cortex-A7 CPU, and a HiFi4 DSP to provide the high-efficient computing power. It supports the full format decoding such as H.265, H.264, MPEG-1/2/4, JPEG, etc. The independent encoder can encode in JPEG or MJPEG. Integrated multi ADCs/DACs and I2S/PCM/DMIC/OWA audio interfaces can work seamlessly with the CPU to accelerate multimedia algorithms and improve the user experience. T113-i supports RGB/LVDS/MIPI DSI/CVBS OUT display output interfaces to meet the requirements of the different screen display. T113-i comes with extensive connectivity and interfaces, such as USB, SDIO, EMAC, TWI, UART, SPI, PWM, GPADC, LRADC, TPADC, IR TX&RX, etc. Besides, T113-i can connect with other different peripherals like Wi-Fi and BT via SDIO and UART.

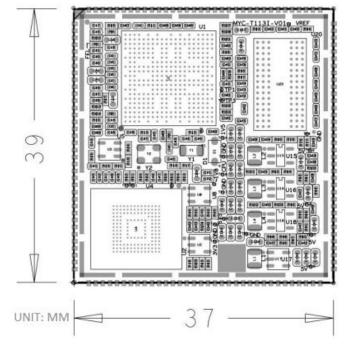
Features	Description			
CPU	• 64-bit Xuantie C906 RISC-V			
	<ul> <li>Dual-core ARM Cortex -A7</li> <li>32 KB L1 I-cache + 32 KB L1 D-cache per core, and 256 KB L2 cache</li> </ul>			
	• Single-core HiFi4			
DSP	• 32 KB I-cache + 32 KB D-cache			
	● 64 KB I-ram + 64 KB D-ram			
Memory	• DDR2/DDR3, up to 2 GB			
Memory	SD3.0/eMMC 5.0, SPI Nor/NAND Flash			
	• Video decoding			
Video Engine	- H.265 up to 4K@30fps - H.264 up to 4K@24fps			
	- H.263, MPEG-1/2/4, JPEG, Xvid, Sorenson Spark, up to 1080p@60fps			
	Video encoding			
	- JPEG/MJPEG up to 1080p@60fps			
	- Supports input picture scaler up/down			
Disales Fasias	• Allwinner SmartColor2.0 post processing for an excellent display experience			
Display Engine	<ul> <li>Supports de-interlace (DI) up to 1080p@60fps</li> <li>Supports G2D hardware accelerator including rotate, mixer, lbc decompression</li> </ul>			
	CVBS OUT interface, supporting NTSC and PAL format			
	RGB LCD output interface up to 1920 x 1080@60fps			
Video OUT	Dual link LVDS interface up to 1920 x 1200@60fps			
	• 4-lane MIPI DSI interface up to 1920 x 1080@60fps			
	8-bit parallel CSI interface			
Video IN	CVBS IN interface, supporting NTSC and PAL format			
	• 2 DACs and 3 ADCs			
Audio	• Analog audio interfaces: MICIN1P/N, MICIN2P/N, MICIN3P/N, FMINL/R, LINEINL/			
	R, LINEOUTLP/N, LINEOUTRP/N, HPOUTL/R			
	Digital audio interfaces: 12S/PCM, DMIC, OWA IN/OUT			
	USB2.0 OTG, USB2.0 Host			
Connectivity	• SDIO 3.0, SPI x 2, UART x 6, TWI x 4, CAN x 2			
	<ul> <li>PWM (8-ch), GPADC (2-ch), LRADC (1-ch), TPADC (4-ch), IR TX&amp;RX</li> <li>10/100/1000M EMAC with RMII and RGMII interfaces</li> </ul>			
Doglegge				
Package	LFBGA 337 balls, 13 mm x 13 mm			

Features of T113-i Processor





Allwinner T113-i Block Diagram



MYC-YT113i Dimensions Chart





The MYC-YT113i CPU Module takes full features of T113-i processor and the main features are characterized as below:

#### **Mechanical Parameters**

Dimensions: 37mm x 39mm
PCB Layers: 8-layer design
Power supply: +5V/1A

• Working temperature: -40~85 Celsius (industrial grade)

#### **Processor**

- Allwinner T113-i processor
  - Up to 1.2GHz Dual-core Arm Cortex-A7 CPU
  - Single-core HiFi4 DSP
  - Supports H.265/H.264 4K video decoding

# **External Memory**

- 512MB/1GB DDR3
- 4GB/8GB eMMC
- 32KB EEPROM

# **Peripherals and Signals Routed to Pins**

- 1.0mm pitch 140-pin Stamp Hole Expansion Interface + 50-pin LGA
  - 1 x RGMII/RMII
  - 2 x USB2.0
  - 6 x UART
  - 2 x CAN
  - 4 x TWI
  - 2 x SPI
  - 1 x GPADC and 4 x TPADC
  - 1 x MIPI DSI
  - 2 x LVDS
  - 1 x RGB
  - 1 x CVBS Out (TV Out)
  - 1 x Parallel CSI
  - 2 x CVBS In (TV In)
  - 2 x I2S
  - Up to 81 GPIOs

Note: the peripheral signals brought out to the expansion interface are listed in maximum number. Some signals are reused. Please refer to the processor datasheet and the CPU Module pinout description file.





# **Software Features**

The MYC-YT113i CPU Module supports Linux OS and comes with complete software package. The kernel and many peripheral drivers are available in source code to assist clients to expedite their development. The following are a summary of the software features:

Item	Feature	Description	Source Code
Bootloader	U-boot	Boot boot program uboot_2018.05	YES
Linux kernel	Linux kernel	Customized base on official kernel_5.4.61 version	YES
Device driver	USB Host	USB Host driver	YES
	USB OTG	USB OTG driver	YES
	I2C	I2C bus driver	YES
	SPI	SPI bus driver	YES
	Ethernet	YT8531SH driver	YES
	SDHI	EMMC/SD card storage driver	YES
	LVDS	LCD driver	YES
	Touch	Touch screen driver	YES
	Audio	SPDIF driver	YES
	Watchdog	Watchdog driver	YES
	4G/5G	4G/5G driver	YES
	PWM	PWM control driver	YES
	ADC	ADC driver	YES
	RTC	RTC driver	YES
	GPIO	Universal GPIO driver	YES
	UART	RS232/RS485/TTL driver	YES
	CAN	CAN driver	YES
	WIFI	RTL8731BU driver	YES
Images	t113i_linux_myir_emmc_core	Image built with Buildroot, excluding GUI interface	YES
	t113i_linux_myir_emmc_full	A fully functional image built with Buildroot	YES

MYC-YT113i Software Features





### **Order Information**

Product Item	Part No.	Packing List	
	MYC-YT113i-4E512D-110-I	✓ One MYC-YT113i CPU Module	
MYC-YT113i CPU Module	MYC-YT113i-8E512D-110-I		
	MYC-YT113i-8E1D-110-I		
	MYD-YT113i-4E512D-110-I	<ul> <li>✓ One MYD-YT113i Development Board (including MYC-YT113i CPU Module)</li> <li>✓ One USB to UART Debug cable</li> <li>✓ One 12V/2A Power adapter</li> </ul>	
MYD-YT113i Development Board	MYD-YT113i-8E512D-110-I		
	MYD-YT113i-8E1D-110-I	<ul><li>✓ One DC Power jack adapter</li><li>✓ One Quick Start Guide</li></ul>	
MY-LVDS070C 7-inch LCD Module	MY-LVDS070C		
MY-WIREDCOM RPI Module	MY-WIREDCOM		

### Note:

- 1. One MYD-YT113i Development Board includes one CPU module MYC-YT113i mounted on the base board. If you need more CPU module, you can order extra ones.
- 2. Discounts are available for bulk orders.
- 3. We provide OEM/ODM services to reduce time and save cost for customers.



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